



SamHop Microelectronics Corp.



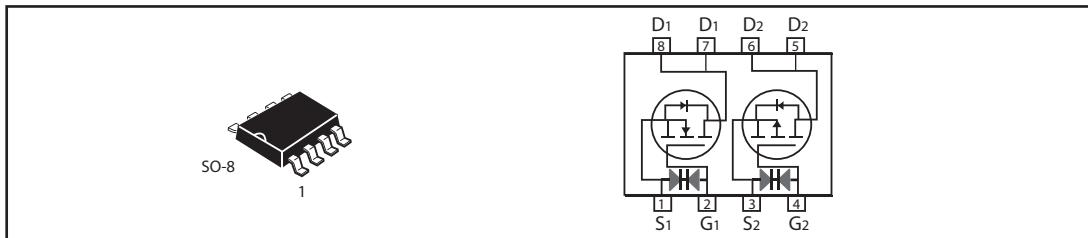
STM8309

Oct.13, 2006

Dual Enhancement Mode Field Effect Transistor (N and P Channel)

PRODUCT SUMMARY (N-Channel)		
V _{DSS}	I _D	R _{DSON} (mΩ) Max
30V	7A	23 @ V _{GS} = 10V
		30 @ V _{GS} = 4.5V

PRODUCT SUMMARY (P-Channel)		
V _{DSS}	I _D	R _{DSON} (mΩ) Max
-30V	-6A	35 @ V _{GS} = -10V
		52 @ V _{GS} = -4.5V



ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	V _{DS}	30	-30	V
Gate-Source Voltage	V _{GS}	± 20	± 20	V
Drain Current-Continuous @ $T_J=25^\circ C$ -Pulsed ^b	I _D	7	-6	A
	I _{DM}	28	-24	A
Drain-Source Diode Forward Current ^a	I _S	1.7	-1.7	A
Maximum Power Dissipation ^a	P _D	2.0		W
Operating Junction and Storage Temperature Range	T _J , T _{TSG}	-55 to 150		°C

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Ambient ^a	R _{θJA}	62.5	°C/W
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N-Channel ELECTRICAL CHARACTERISTICS (TA = 25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ ^c	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V, I _D =250uA	30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =24V, V _{GS} =0V		1		uA
Gate-Body Leakage	I _{GSS}	V _{GS} =±20V, V _{DS} =0V		±10		uA
ON CHARACTERISTICS ^b						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	1.0	1.9	3	V
Drain-Source On-State Resistance	R _{D(S(ON))}	V _{GS} =10V, I _D =7A		17	23	m ohm
		V _{GS} =4.5V, I _D =5A		23	30	m ohm
On-State Drain Current	I _{D(ON)}	V _{DS} =15V, V _{GS} =10V	20			A
Forward Transconductance	g _{FS}	V _{DS} =10V, I _D =7A		14		S
DYNAMIC CHARACTERISTICS ^c						
Input Capacitance	C _{ISS}	V _{DS} =15V, V _{GS} =0V f=1.0MHz		680		pF
Output Capacitance	C _{OSS}			190		pF
Reverse Transfer Capacitance	C _{RSS}			115		pF
SWITCHING CHARACTERISTICS ^c						
Turn-On Delay Time	t _{D(ON)}	V _{DD} =15V, I _D =7A, R _L =2.1 ohm, V _{GS} =10V, R _{GEN} =6 ohm		12		ns
Rise Time	t _r			17.5		ns
Turn-Off Delay Time	t _{D(OFF)}			41		ns
Fall Time	t _f			15		ns
Total Gate Charge	Q _g	V _{DS} =15V, I _D =7A, V _{GS} =10V		11		nC
		V _{DS} =15V, I _D =7A, V _{GS} =4.5V		5.5		nC
Gate-Source Charge	Q _{gs}	V _{DS} =15V, I _D =7A, V _{GS} =10V		1.7		nC
Gate-Drain Charge	Q _{gd}			3.3		nC

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P-Channel ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ ^c	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=-24\text{V}, V_{\text{GS}}=0\text{V}$		-1		μA
Gate-Body Leakage	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$		± 10		μA
ON CHARACTERISTICS^b						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1	-1.9	-3	V
Drain-Source On-State Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}= -5\text{A}$		29	35	m ohm
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}= -4\text{A}$		44	52	m ohm
On-State Drain Current	$I_{\text{D(ON)}}$	$V_{\text{DS}} = -15\text{V}, V_{\text{GS}} = -10\text{V}$	-20			A
Forward Transconductance	g_{FS}	$V_{\text{DS}} = -15\text{V}, I_{\text{D}} = - 5\text{A}$		8.5		S
DYNAMIC CHARACTERISTICS^c						
Input Capacitance	C_{ISS}	$V_{\text{DS}} = -15\text{V}, V_{\text{GS}} = 0\text{V}$ $f = 1.0\text{MHz}$		870		pF
Output Capacitance	C_{OSS}			225		pF
Reverse Transfer Capacitance	C_{RSS}			125		pF
SWITCHING CHARACTERISTICS^c						
Turn-On Delay Time	$t_{\text{D(ON)}}$	$V_{\text{D}} = -15\text{V},$ $R_{\text{L}}=15 \text{ ohm},$ $I_{\text{D}} = -1\text{A},$ $V_{\text{GEN}} = -10\text{V},$ $R_{\text{GEN}}=6 \text{ ohm}$		12		ns
Rise Time	t_{r}			18		ns
Turn-Off Delay Time	$t_{\text{D(OFF)}}$			70		ns
Fall Time	t_{f}			40		ns
Total Gate Charge	Q_{g}	$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-5\text{A}, V_{\text{GS}}=-10\text{V}$		15		nC
		$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-5\text{A}, V_{\text{GS}}=-4.5\text{V}$		7.5		nC
Gate-Source Charge	Q_{gs}	$V_{\text{DS}} = -15\text{V}, I_{\text{D}} = - 5\text{A},$ $V_{\text{GS}} = -10\text{V}$		1.7		nC
Gate-Drain Charge	Q_{gd}			4.5		nC

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ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ ^c	Max	Unit
DRAIN-SOURCE DIODE CHARACTERISTICS ^b						
Diode Forward Voltage	V_{SD}	$V_{GS} = 0V, I_S = 1.7A$ $V_{GS} = 0V, I_S = -1.7A$	N-Ch		0.8 -0.8	1.2 -1.2

Notes

- a. Surface Mounted on FR4 Board, $t \leq 10\text{ sec}$.
 - b. Pulse Test: Pulse Width $\leq 300\ \mu\text{s}$, Duty Cycle $\leq 2\%$.
 - c. Guaranteed by design, not subject to production testing.
- N-Channel

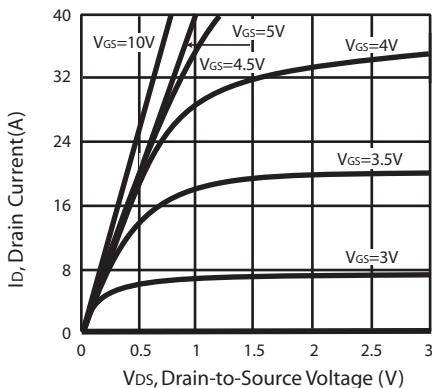


Figure 1. Output Characteristics

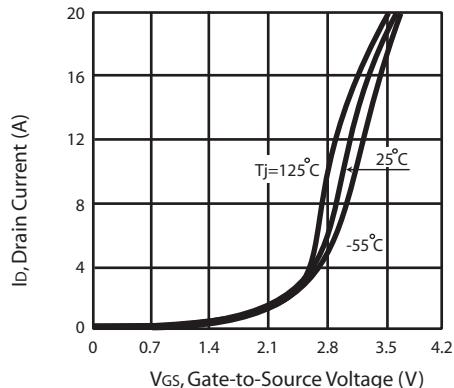


Figure 2. Transfer Characteristics

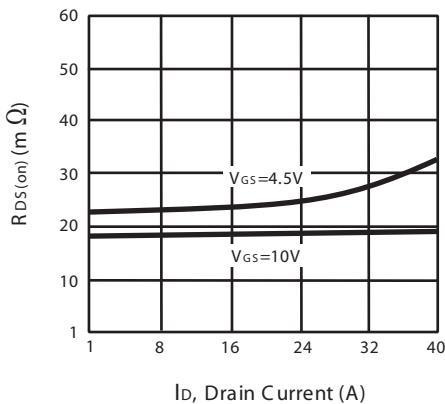


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

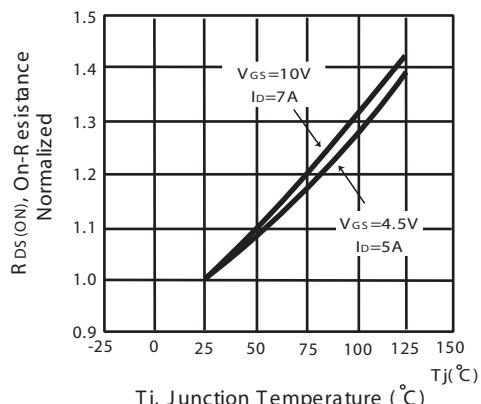


Figure 4. On-Resistance Variation with Drain Current and Temperature

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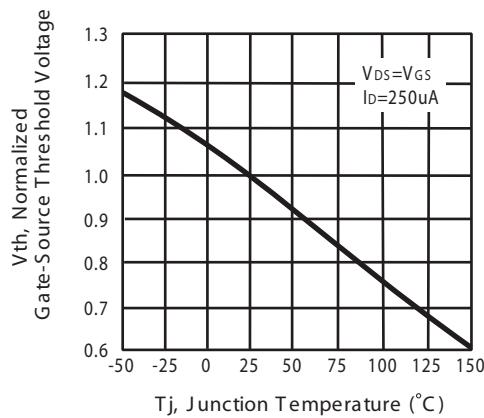


Figure 5. Gate Threshold Variation with Temperature

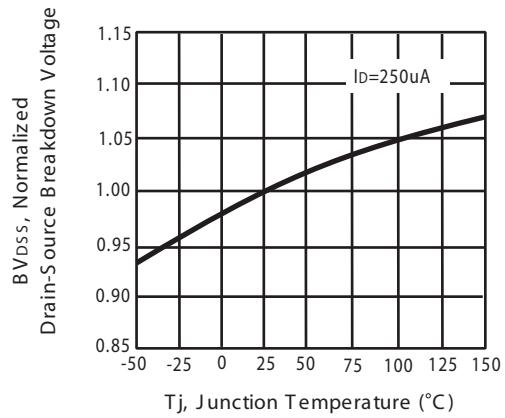


Figure 6. Breakdown Voltage Variation with Temperature

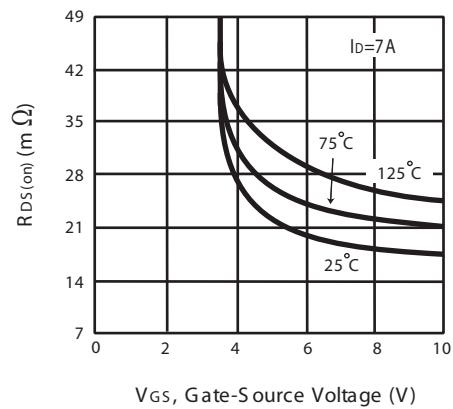


Figure 7. On-Resistance vs. Gate-Source Voltage

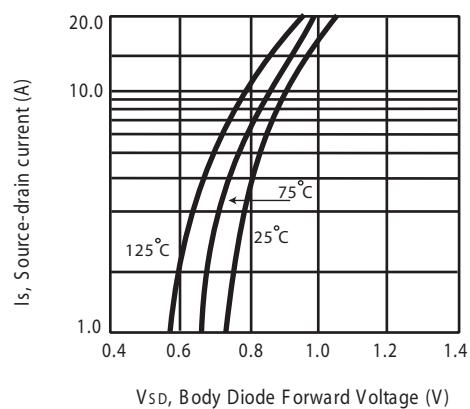


Figure 8. Body Diode Forward Voltage Variation with Source Current

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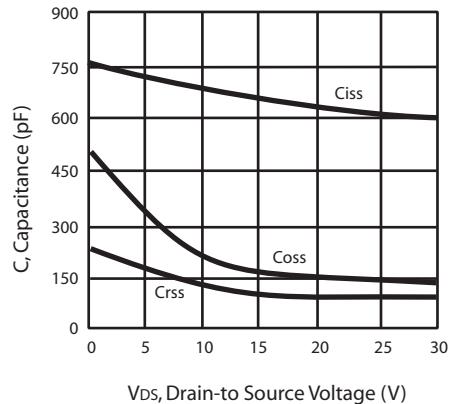


Figure 8. Capacitance

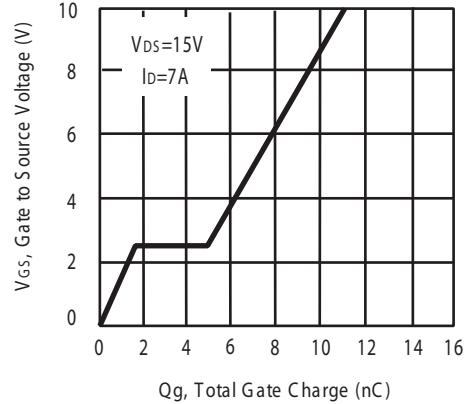


Figure 9. Gate Charge

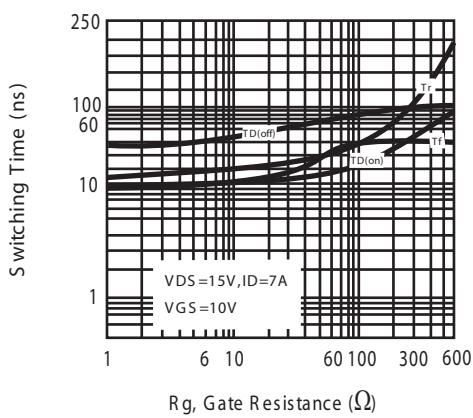


Figure 11. switching characteristics

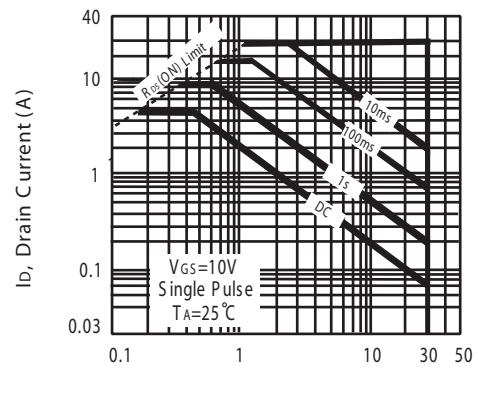


Figure 10. Maximum Safe Operating Area

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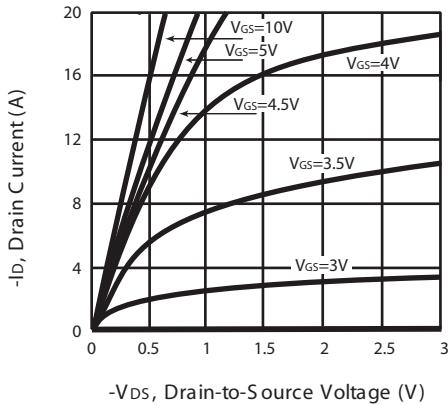


Figure 1. Output Characteristics

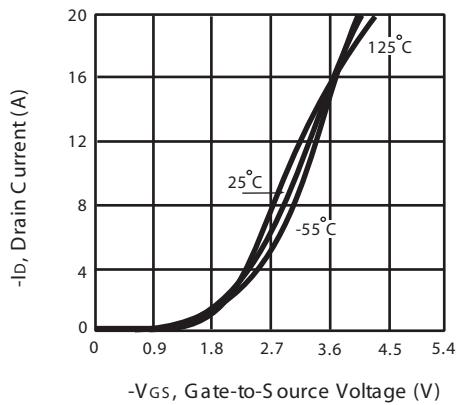


Figure 2. Transfer Characteristics

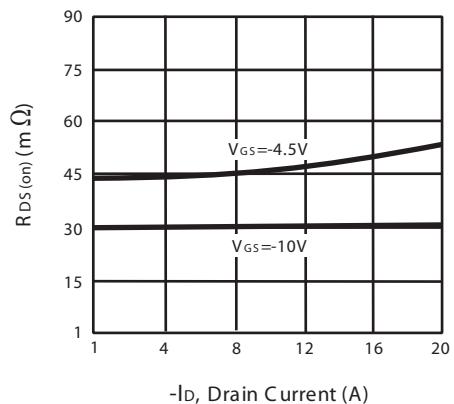


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

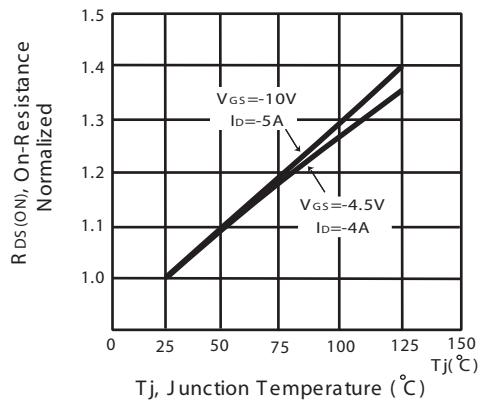


Figure 4. On-Resistance Variation with Drain Current and Temperature

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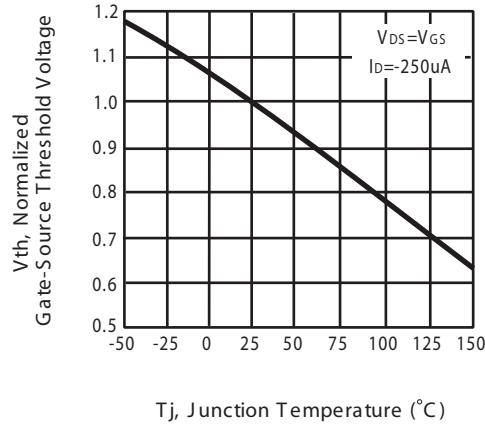


Figure 5. Gate Threshold Variation with Temperature

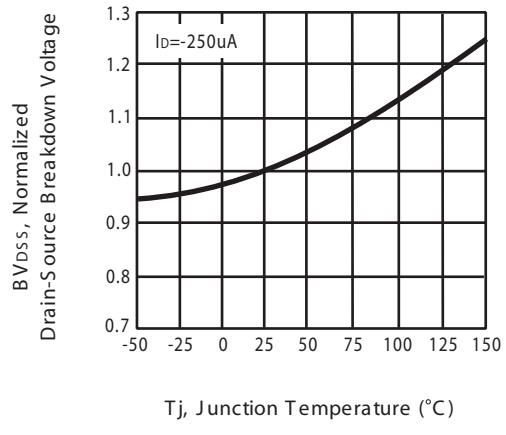


Figure 6. Breakdown Voltage Variation with Temperature

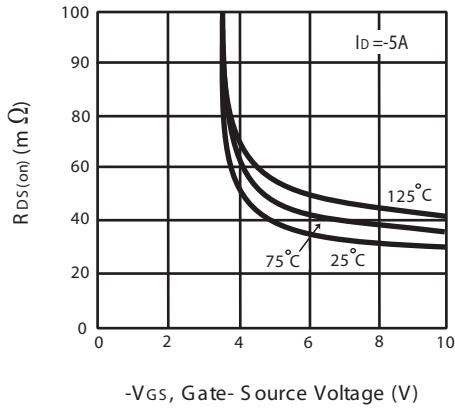


Figure 7. On-Resistance vs. Gate-Source Voltage

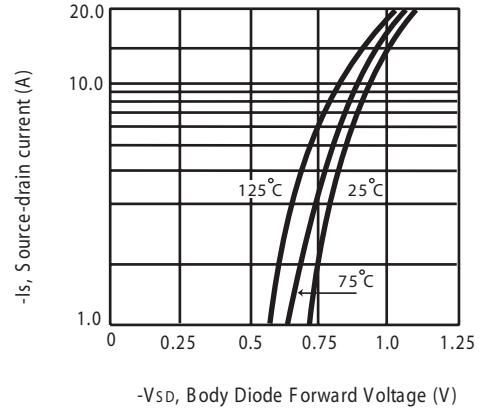


Figure 8. Body Diode Forward Voltage Variation with Source Current

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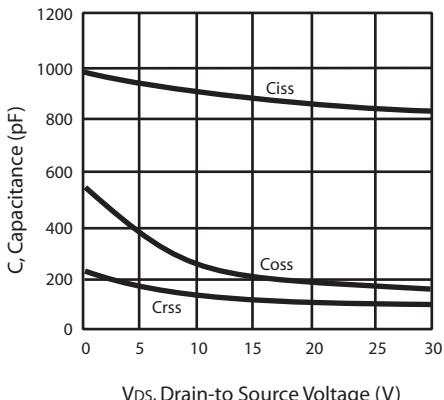


Figure 8. Capacitance

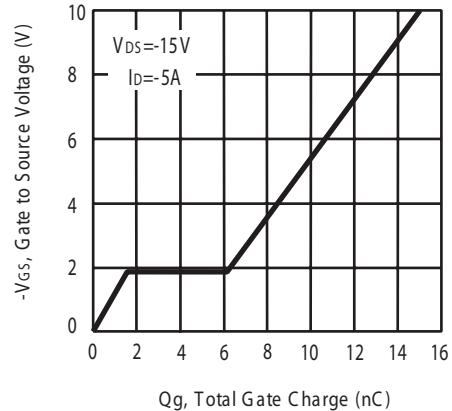


Figure 9. Gate Charge

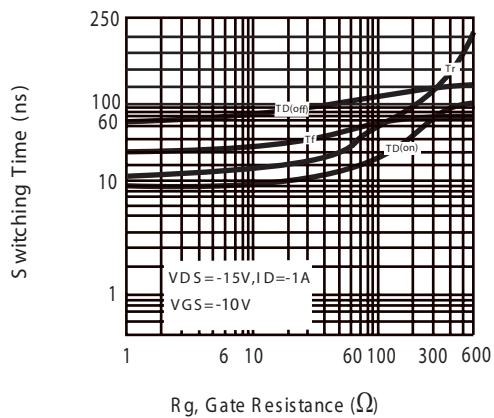


Figure 11. switching characteristics

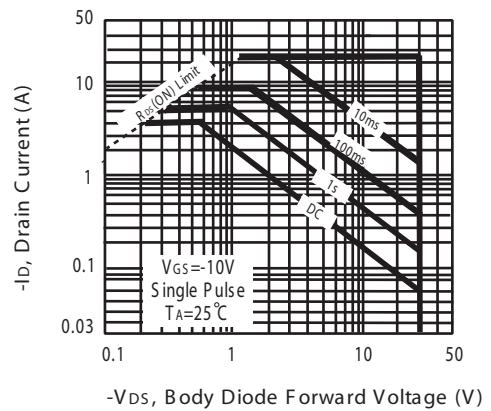


Figure 10. Maximum Safe
Operating Area

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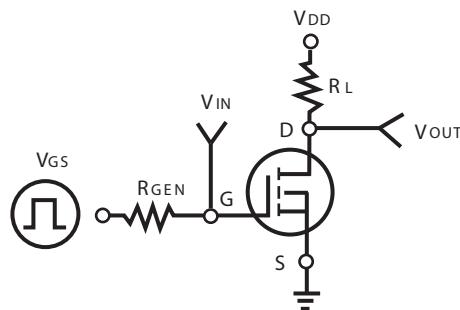


Figure 13. Switching Test Circuit

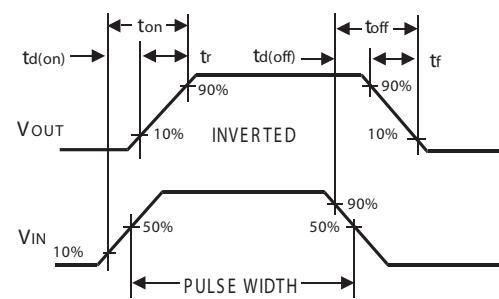
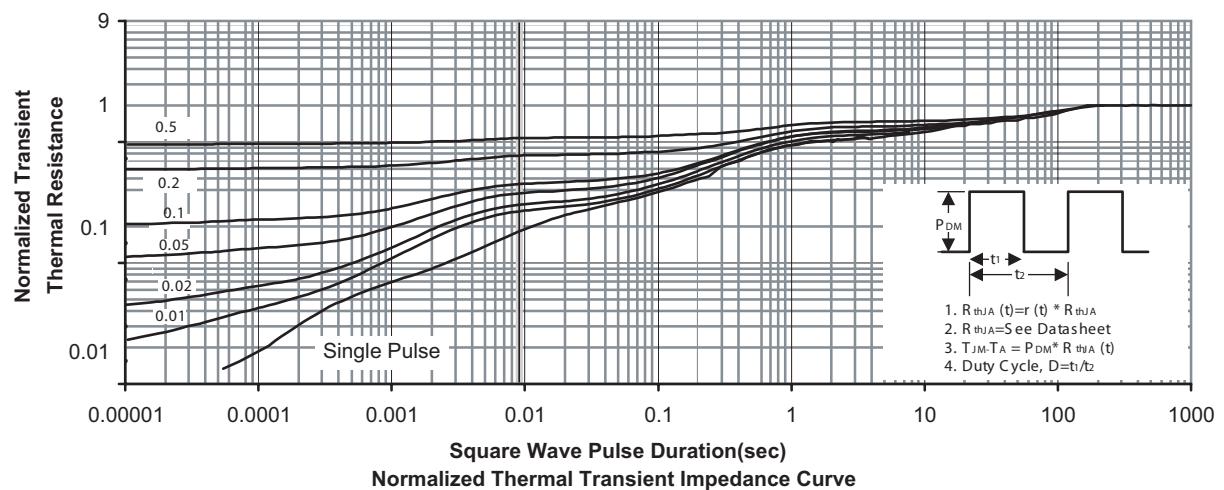
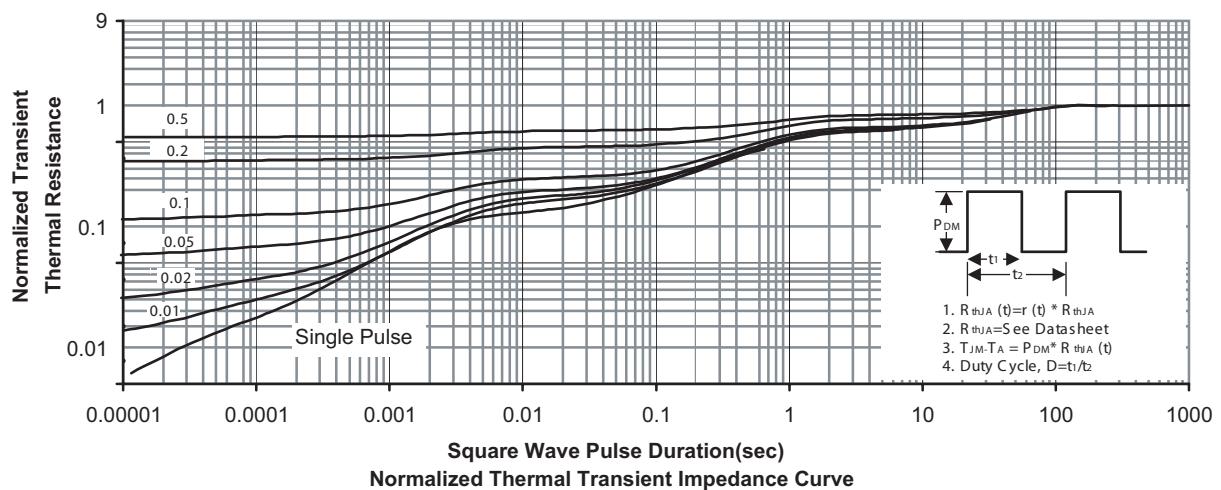


Figure 14. Switching Waveforms

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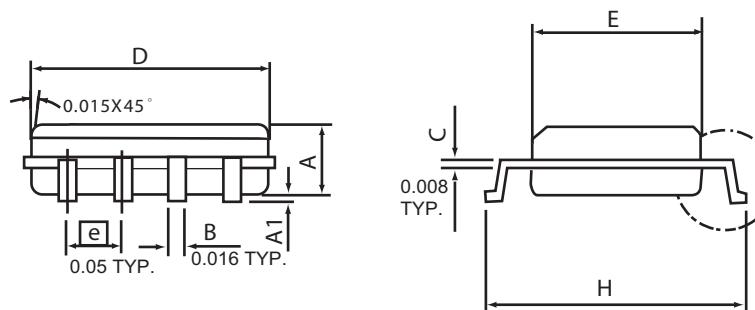
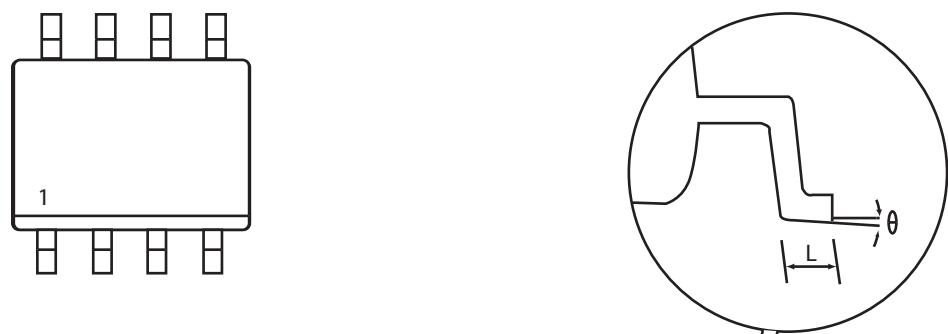
P-Channel



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PACKAGE OUTLINE DIMENSIONS

SO-8

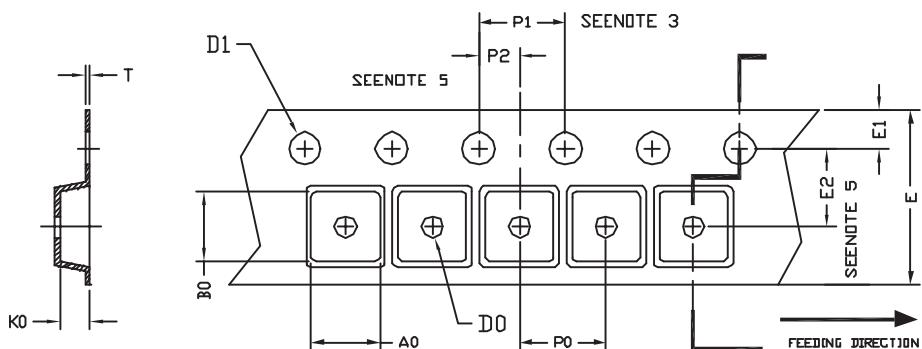


SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.053	0.069
A1	0.10	0.25	0.004	0.010
D	4.80	4.98	0.189	0.196
E	3.81	3.99	0.150	0.157
H	5.79	6.20	0.228	0.244
L	0.41	1.27	0.016	0.050
θ	0°	8°	0°	8°

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SO-8 Tape and Reel Data

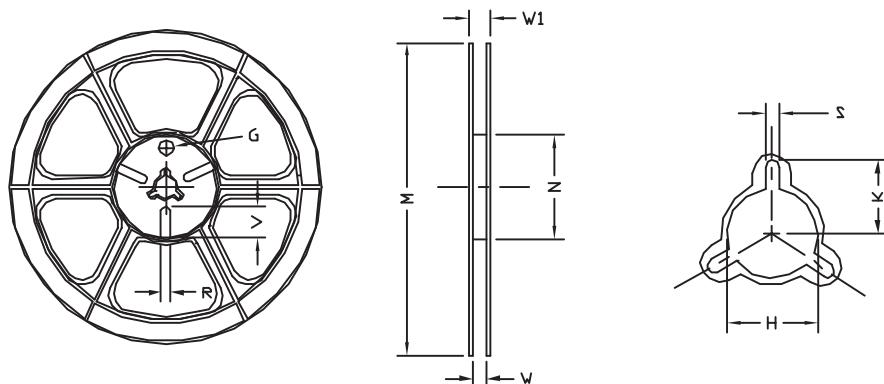
SO-8 Carrier Tape



unit:mm

PACKAGE	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T
SOP 8N 150mil	6.40	5.20	2.10	$\phi 1.5$ (MIN)	$\phi 1.5$ $+0.1$ -0.0	12.0 ± 0.3	1.75	5.5 ± 0.05	8.0	4.0	2.0 ± 0.05	0.3 ± 0.05

SO-8 Reel



UNIT:mm

TAPE SIZE	REEL SIZE	M	N	W	W1	H	K	S	G	R	V
12 mm	$\phi 330$	330 ± 1	62 ± 1.5	12.4 ± 0.2	$16.8 - 0.4$	$\phi 12.75 \pm 0.15$	---	2.0 ± 0.15	---	---	---